



Main page > Repair Equipment > Soldering Equipment > Stencil BGA kit > BGA TWTK-BGAP-25 plating kit

BGA TWTK-BGAP-25 plating kit

Product ID: 1874

Price: **9.00 EUR**

Product weight: **0.01 kg**

Description:

BGA TWTK-BGAP-25 plating kit it's a 25 set matrix for that's needed tool when you have to exchange BGA parts of your phone. It's supports Nokia chipset as 3210/8850/8810/8210 IC, 3310/8210 MD, 8210 IC, 6210 IC, 8810 CPU, 3220 MF, 6230 RAM, 3220 CPU, 7250 CPU, 7250/7200 Flash, 7610/7260 UEM, 3220 Flash, 3100 CPU, 6230 UEM, 6230 Blue EarPhone, 6230 CPU, 8310/6230 Flash, 3310/3210/8850/8210 CPU, 8310 IC, 6230 CPU. Click to link for bigger photo - [LINK](#)

Contact details:

Telefon: +48 17 227 00 25

Infolinia: 0 801 671 717

E-mail: biuro@multi-com.pl

Skype: Multi-COM

Adress:

Multi-COM Sp. z o.o.

ul. Stanisława Krzaklewskiego 31b

36-100 Kolbuszowa

POLSKA

[Go to the product](#)

